



Product Change Notification

111353 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 111353 - 01

**Change Title: Intel® Desktop Board D2700DC,
Boxed and Bulk,
PCN 111353-01, Product Material,
Change Heat Sink,
Reason for Revision: Add IDT
Part**

Date of Publication: March 07, 2012

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Mar 19, 2012
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Description of Change to the Customer:

Reason for Revision: Add IDT Part

1. Reduce the height of the heatsink from 32mm to 25mm to improve compatibility with Mini ITX chassis. The length and width of the heatsink is not changed.
2. Replace the clock chip with an IDT part in order to improve supply availability.

Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BOXD2700DC	915835	G32420-600	G32420-601
BLKD2700DC	915844	G32420-600	G32420-601

PCN Revision History:

Date of Revision:

February 28, 2012

March 7, 2012

Revision Number:

00

01

Reason:

Originally Published PCN

Add IDT Part